



**Apparatus, And Corresponding Method, For Chemically
Etching Substrates**

Abstract

5 An apparatus, and a corresponding method, for chemically
etching the copper foil of a copper foil-clad substrate are disclosed.
Significantly, this apparatus includes fluid jet injectors which
serve to produce jets of chemical etchant. These fluid jet injectors
are arranged so as to simultaneously achieve a relatively high etch
rate and a relatively high etch uniformity.

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